SOD-123

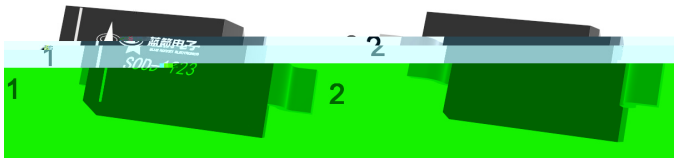
Zener Diode in a SOD-123 Plastic Package.

500mW ,

500mW power dissipation, medium current, automated assembly processes, HF Product.

2.4V-39V

2.4V to 39V wide zener voltage range applications.



PIN1:Cathode PIN2:Anode

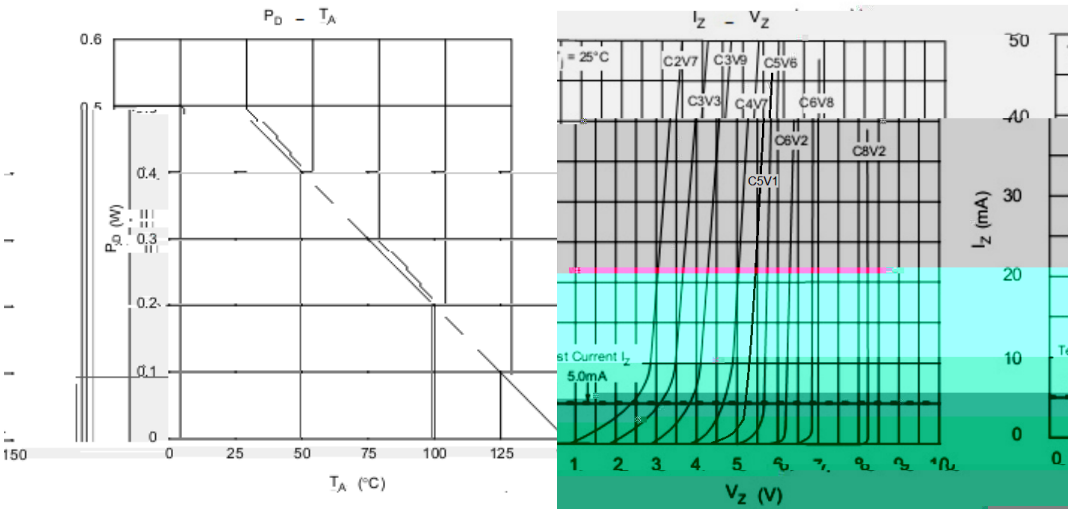
Parameter	Symbol	Rating	Unit
Forward Voltage (Note 2) (I_F=10mA)	V_F	0.9	V
Power Dissipation(Note 1)	P_D	500	mW
Typical Thermal Resistance Junction to Ambient	R_{JA}	305	/W

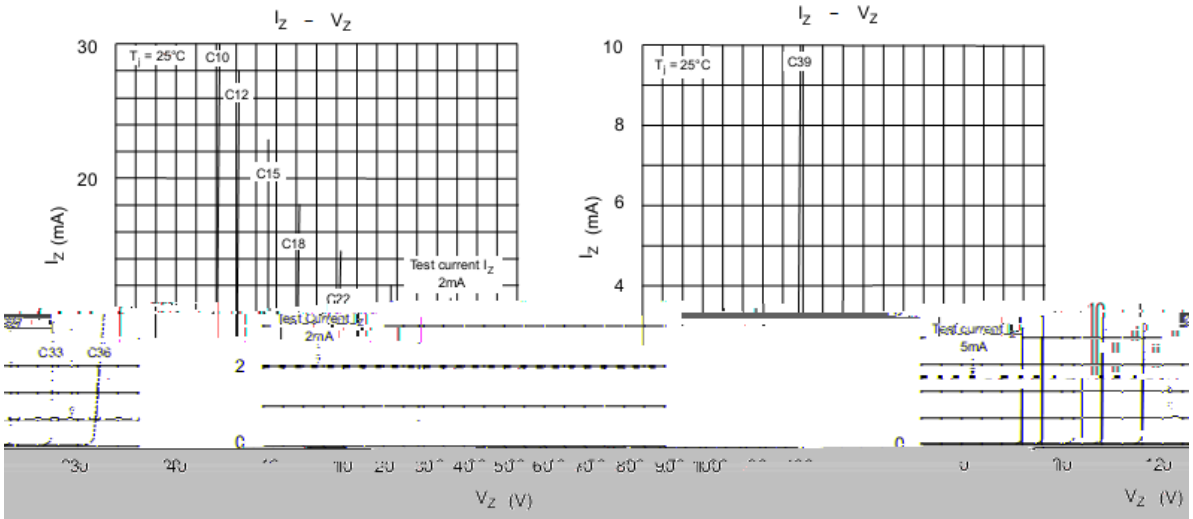
Junction and Storage Temperature Range A75.7(ge)]TJ21.7859ion 2 . Junction3J21.7859ion 2 . 0 0 1/64w[10 10.5 312.94 .48 .j,2.4603 Tm(V)Tj7.017

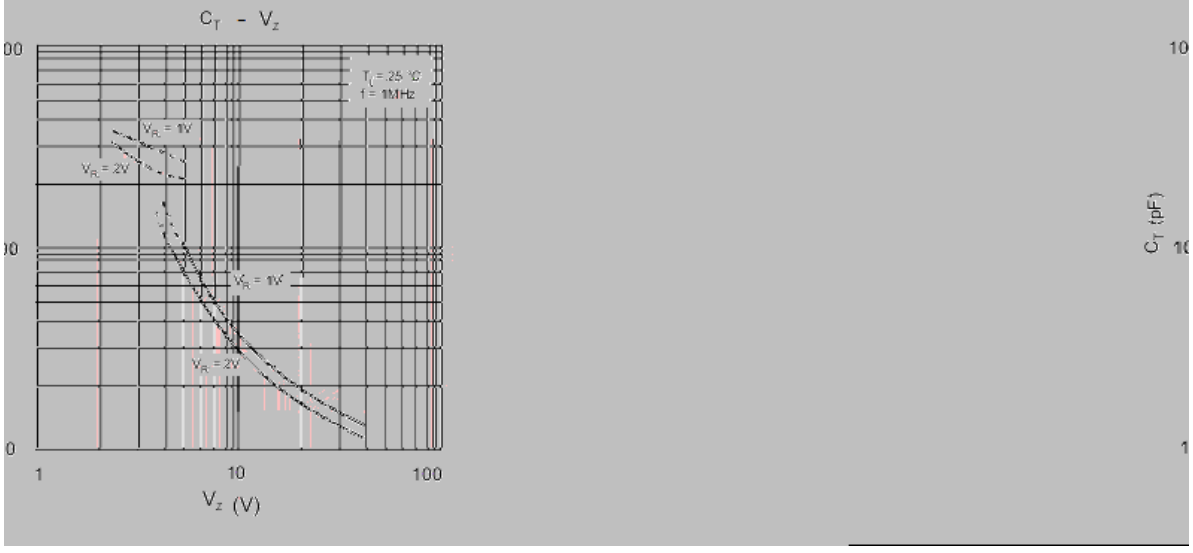
/ Electrical Characteristics(Ta=25)

ype mber	Marki ng Code	Zener Voltage Range (Note 2)				Maximum Zener mpedance (Note 3)			Maximum Reverse Current (Note 2)		Typical Temperature Coefficient @I_{ZTC} mV/ºC		Test Curre nt I_{ZTC}
		V_z @I_{ZT}			I_{ZT}	Z_{ZT} @I_{ZT}	Z_{ZK} @I_{ZK}	I_{ZK}	I_R	@V_R			
		Nom (V)	Min (V)	Max (V)	mA			mA	uA	V	Min	Max	mA
52C11	HWG	11	10.4	11.6	5	20	150	1	0.1	8	5.4	9	5
52C12	HWH	12	11.4	12.7	5	25	150	1	0.1	8	6	10	5
52C13	HWI	13	12.4	14.1	5	30	170	1	0.1	8	7	11	5
52C15	HWJ	15	13.8	15.6	5	30	200	1	0.1	10.5	9.2	13	5
52C16	HWK	16	15.3	17.1	5	40	200	1	0.1	11.2	10.4	14	5
								1	0.1	12.6	12.4	16	5
								1	0.1	14	14.4	18	5
								1	0.1	15.4	16.4	20	5

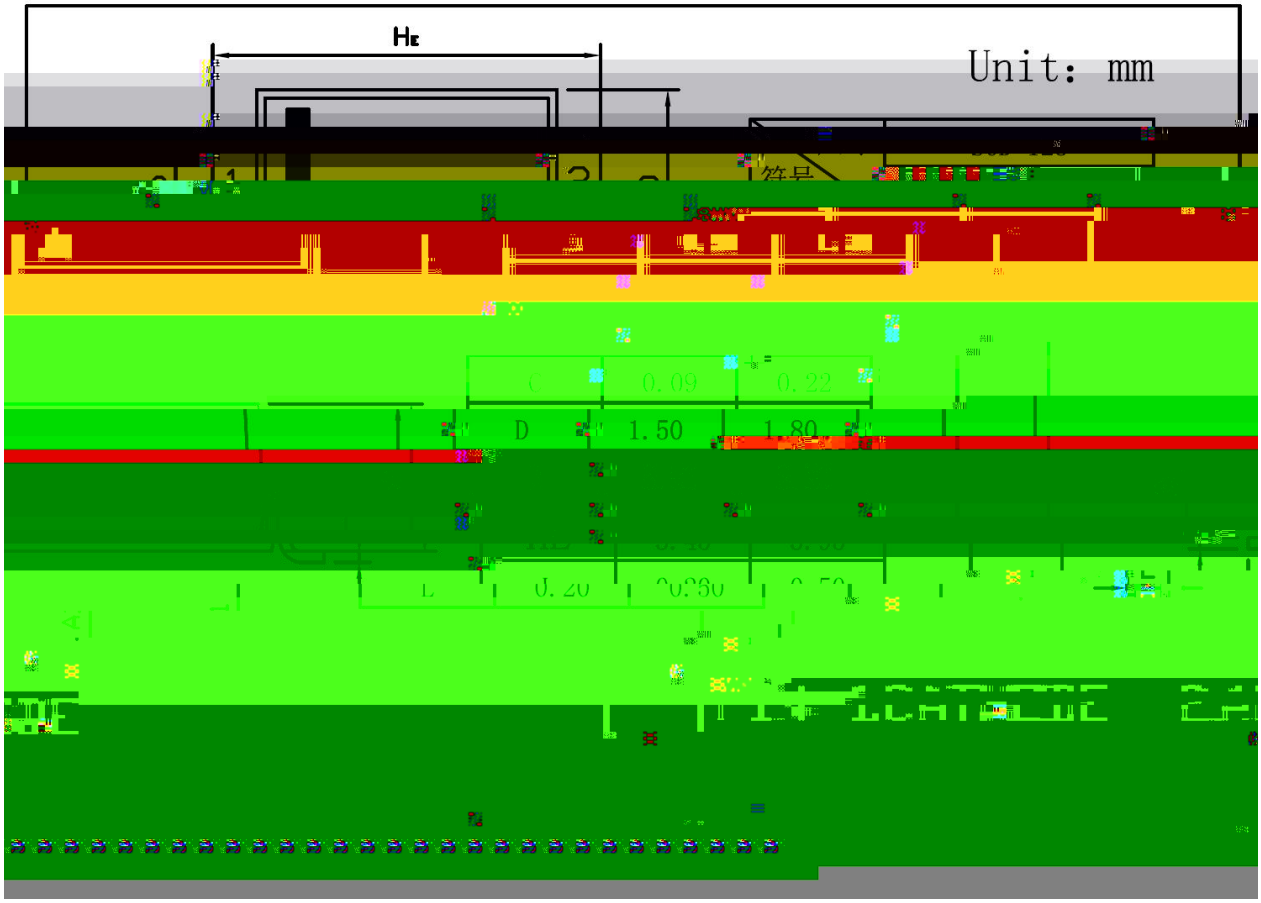
/ Electrical Characteristic Curve







/ Package Dimensions



/ Marking Instructions



H

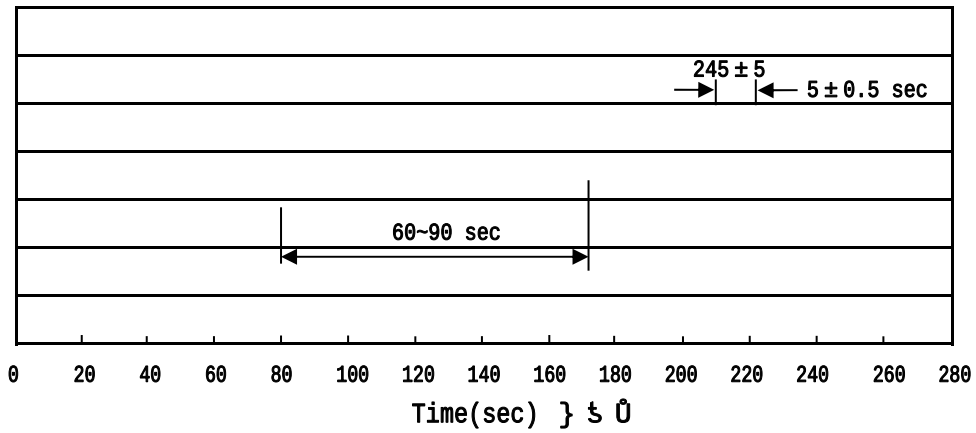
WX

Note:

H: Company Code

WX: Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



			Note:
1	150 180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5	5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3	2 10 /sec.		3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOD-123	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices